

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHUTESH KRISHNAN	07/21/2014
YUN SUNG WON	07/21/2014
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Street Address:	5005 E. MCDOWELL ROAD
Internal Address:	MD-A700
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85008
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14339524
CORRESPONDENCE DATA	
Fax Number:	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	602-244-6648
Email:	PATENTS@ONSEMI.COM
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Address Line 1:	5005 E. MCDOWELL ROAD
Address Line 2:	MD-A700
Address Line 4:	PHOENIX, ARIZONA 85008
ATTORNEY DOCKET NUMBER:	ONS01305D01
NAME OF SUBMITTER:	KELLY A NELSON
SIGNATURE:	/Kelly A. Nelson/
DATE SIGNED:	07/24/2014
Total Attachments: 2	
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ASSIGNMENT & AGREEMENT

ONS01305D01

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

<u>Name</u>	<u>of (City/State/Country)</u>
Shutesh Krishnan	SEREMBAN, NSDK, MALAYSIA
Yun Sung Won	BAYAN LEPAS, PULAU PINANG, MALAYSIA

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

BONDING STRUCTURE AND METHOD

Attorney Docket No. ONS01305D01

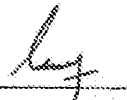
described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.


By (Inventor signature): 
Shutesh Krishnan

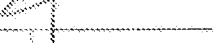
Witnessed by (Witness signature): 

Printed name of Witness: Ashvinder Singh Bhat

Signed and Witnessed on (date): 21st July 2014

.....

By (Inventor signature): 
Yun Sung Won

Witnessed by (Witness signature): 

Printed name of Witness: LIM CHOO KEAN

Signed and Witnessed on (date): 21 JUL 2014